



High-end Power Semiconductor Manufacturer

KP500A 2000V-2800V

Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current			I_{TAV}	500 A		
Repetitive peak off-state voltage			V_{DRM}	2000 – 2800 V		
Repetitive peak reverse voltage			V_{RRM}			
Turn-off time			t_q	250 μ s		
V_{DRM}, V_{RRM}, V	2000	2200	2400	2600	2800	
Voltage code	20	22	24	26	28	
$T_{ij}, ^\circ C$	-60 – 125					

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	500	$T_c=85\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	785	$T_c=85\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	10.0 12.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; 50 Hz ($t_p=10\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\text{ V}$; $t_{GP}=500\text{ }\mu\text{s}$; $di_G/dt=1\text{ A}/\mu\text{s}$
			11.0 13.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; 60 Hz ($t_p=8.3\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\text{ V}$; $t_{GP}=500\text{ }\mu\text{s}$; $di_G/dt=1\text{ A}/\mu\text{s}$
I^2t	Safety factor	A^2s	0.247×10^6	$T_j=T_{j\text{ max}}$	180° half-sine wave; 50 Hz ($t_p=10\text{ ms}$); single pulse; $V_R=0.67\cdot V_{RRM}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\text{ V}$; $t_{GP}=500\text{ }\mu\text{s}$; $di_G/dt=1\text{ A}/\mu\text{s}$
			0.500×10^6 0.720×10^6	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; 50 Hz ($t_p=10\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\text{ V}$; $t_{GP}=500\text{ }\mu\text{s}$; $di_G/dt=1\text{ A}/\mu\text{s}$
			0.500×10^6 0.700×10^6	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; 60 Hz ($t_p=8.3\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\text{ V}$; $t_{GP}=500\text{ }\mu\text{s}$; $di_G/dt=1\text{ A}/\mu\text{s}$

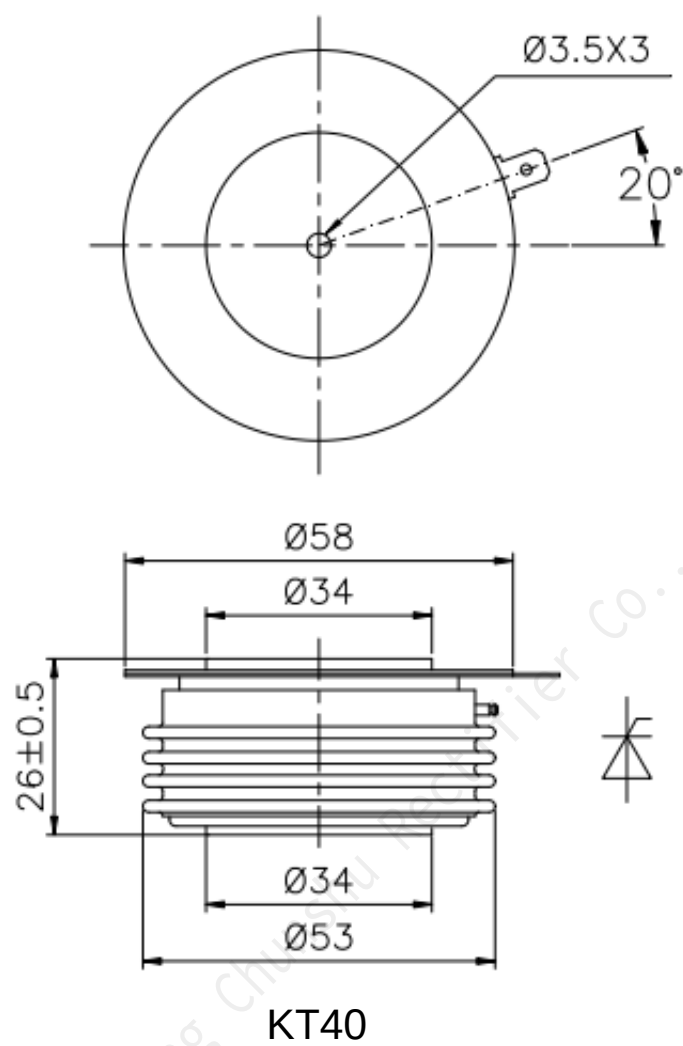
BLOCKING				
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000–2800	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; Gate open
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100–2900	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; single pulse; Gate open
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.75 \cdot V_{DRM}$ $0.75 \cdot V_{RRM}$	$T_j = T_{j\max}$; Gate open
TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j = T_{j\max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/ μ s	400	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = I_{FGM}$; $V_G = 20$ V; $t_{GP} = 500 \mu$ s; $di_G/dt = 1$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60–125	
T_j	Operating junction temperature	°C	-60–125	
MECHANICAL				
F	Mounting force	kN	14.0–16.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	2.20	$T_j=25\text{ }^{\circ}\text{C}; I_{TM}=1570\text{ A}$	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.09	$T_j=T_{j\text{ max}};$	
r_T	On-state slope resistance, max	m Ω	0.755	$0.5\pi I_{TAV} < I_T < 1.5\pi I_{TAV}$	
I_L	Latching current, max	mA	1000	$T_j=25\text{ }^{\circ}\text{C}; V_D=12\text{ V};$ Gate pulse: $I_G=I_{FGM}; V_G=20\text{ V};$ $t_{GP}=500\text{ }\mu\text{s}; di_G/dt=1\text{ A}/\mu\text{s}$	
I_H	Holding current, max	mA	300	$T_j=25\text{ }^{\circ}\text{C};$ $V_D=12\text{ V};$ Gate open	
BLOCKING					
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	100	$T_j=T_{j\text{ max}};$ $V_D=V_{DRM}; V_R=V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μs	1000	$T_j=T_{j\text{ max}};$ $V_D=0.67\cdot V_{DRM};$ Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	2.50 2.00	$T_j=25\text{ }^{\circ}\text{C}$ $T_j= T_{j\text{ max}}$	$V_D=12\text{ V}; I_D=3\text{ A};$ Direct gate current
I_{GT}	Gate trigger direct current, max	mA	250 200	$T_j= 25\text{ }^{\circ}\text{C}$ $T_j= T_{j\text{ max}}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.25	$T_j=T_{j\text{ max}};$ $V_D=0.67\cdot V_{DRM};$	
I_{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current	

SWITCHING					
t _{gd}	Delay time	μs	2.50	T _j =25 °C; V _D =0.4·V _{DRM} ; I _{TM} =I _{TAV} ; Gate pulse: I _G =I _{FGM} ; V _G =20 V; t _{GP} =500 μs; di _G /dt=1 A/μs	
t _q	Turn-off time ²⁾ , max	μs	250	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} = I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67·V _{DRM}	
Q _{rr}	Total recovered charge, max	μC	1950	T _j =T _{j max} ; I _{TM} = 500 A; di _R /dt=-10 A/μs; V _R =100 V;	
t _{rr}	Reverse recovery time, typ	μs	26.0		
I _{rrM}	Peak reverse recovery current, max	A	150		
THERMAL					
R _{thjc}	Thermal resistance, junction to case, max	°C/W	0.0320	Direct current	Double side cooled
R _{thjc-A}			0.0704		Anode side cooled
R _{thjc-K}			0.0576		Cathode side cooled
R _{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0060	Direct current	
MECHANICAL					
w	Weight, typ	g	260		
D _s	Surface creepage distance	mm (inch)	19.44 (0.765)		
D _a	Air strike distance	mm (inch)	12.10 (0.476)		

OVERALL DIMENSIONS



All dimensions in millimeters

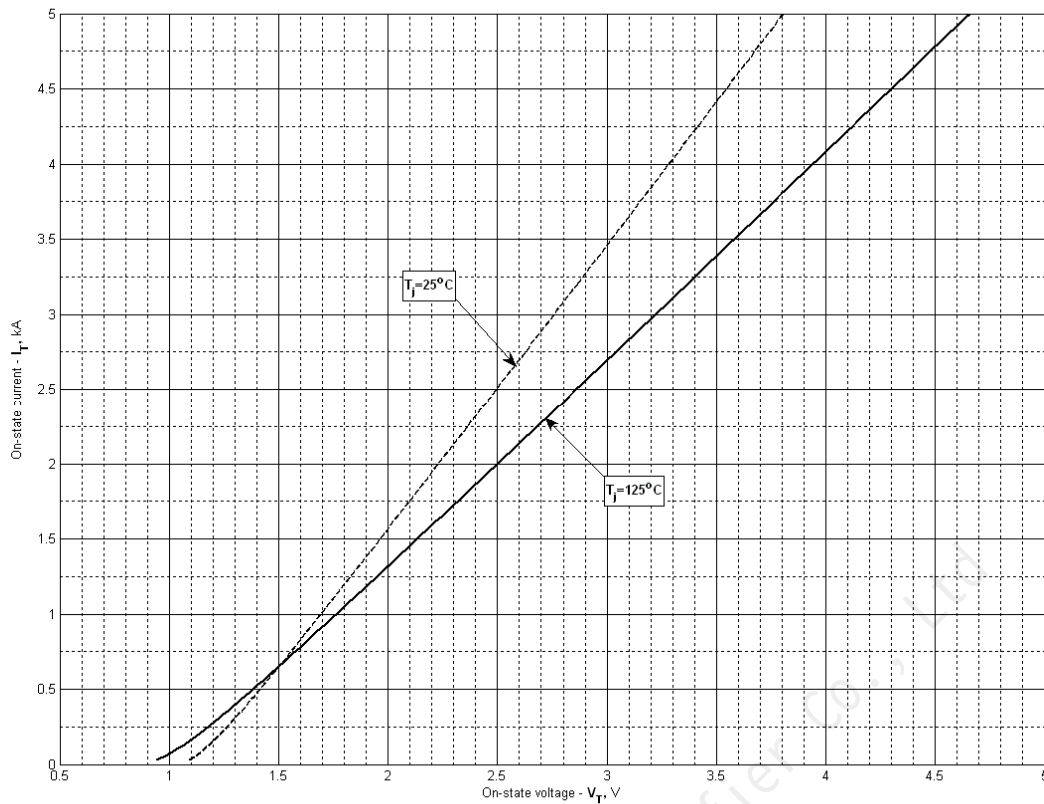


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j\max}$
A	1.031292	0.861860
B	0.483787	0.663978
C	-0.181345	-0.242199
D	0.304070	0.406107

On-state characteristic model (see Fig. 1)

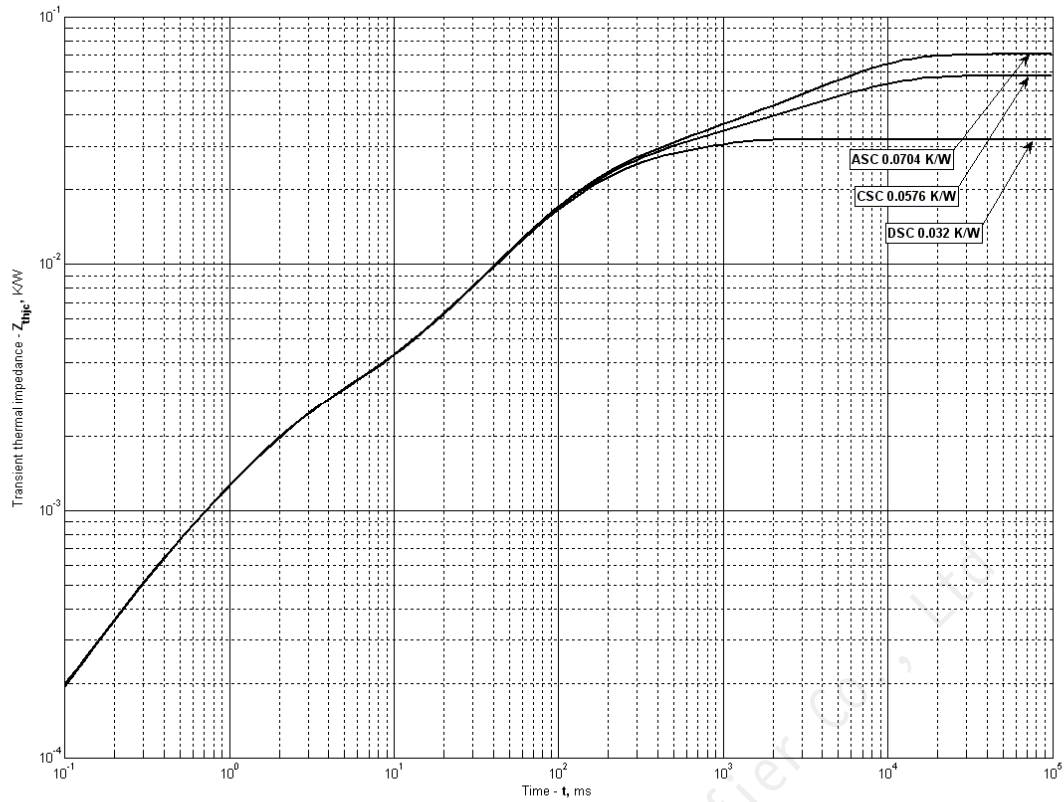


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.000005619	0.01031	0.01922	0.0004148	0.001895	0.0001521
τ_i , s	7.790	0.5094	0.09719	0.01725	0.0016	0.0002257

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.0381	0.008681	0.01867	0.001961	0.0001787	0.002771
τ_i , s	5.351	0.4584	0.09325	0.001734	0.0002174	0.9059

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.02561	0.001472	0.01786	0.001926	0.0001928	0.01052
τ_i , s	5.328	0.1832	0.09031	0.001714	0.0002598	0.525

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

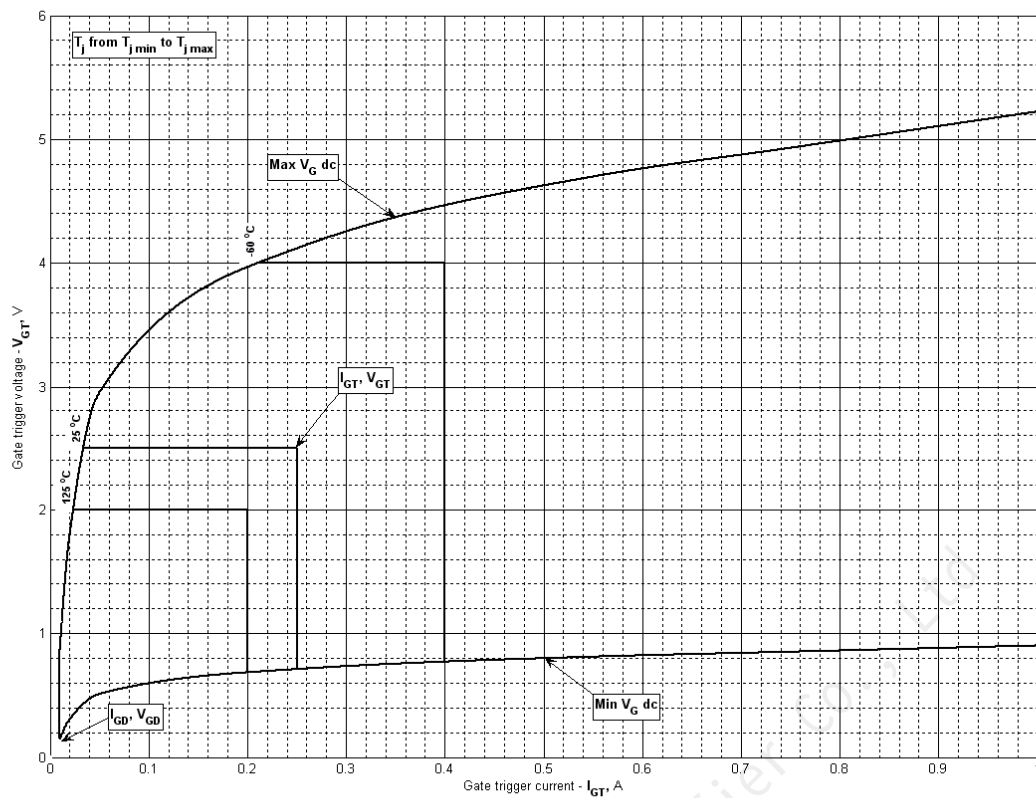


Fig 3 – Gate characteristics – Trigger limits

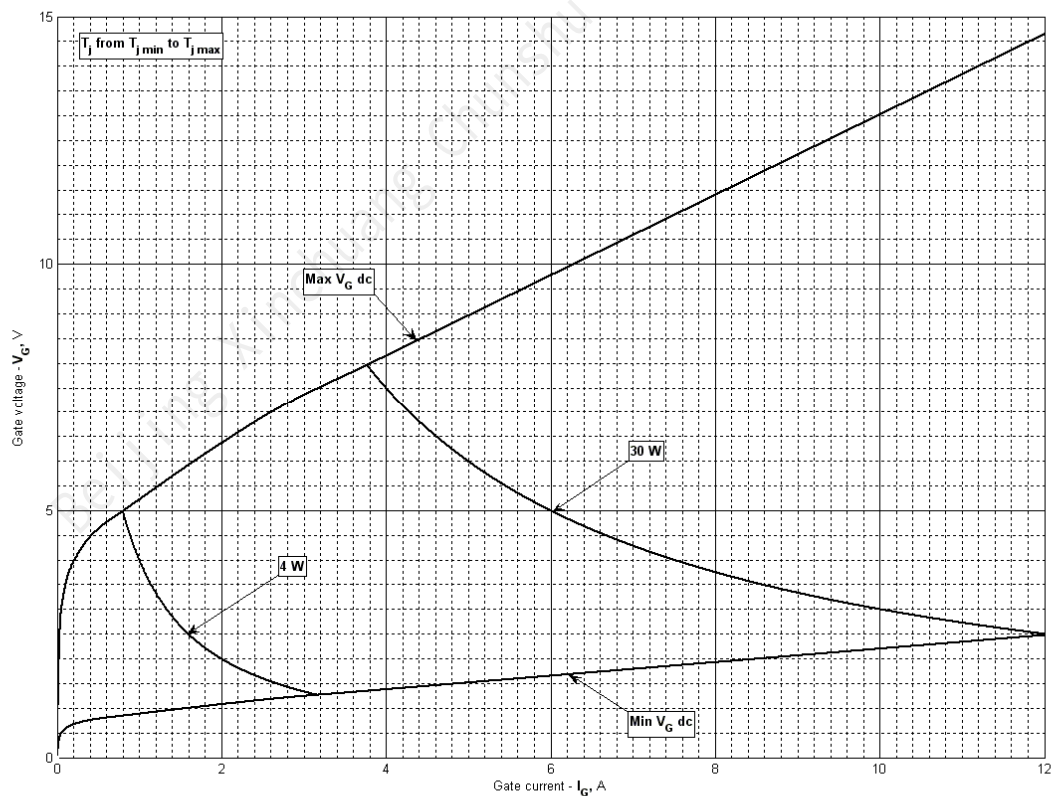


Fig 4 - Gate characteristics –Power curves

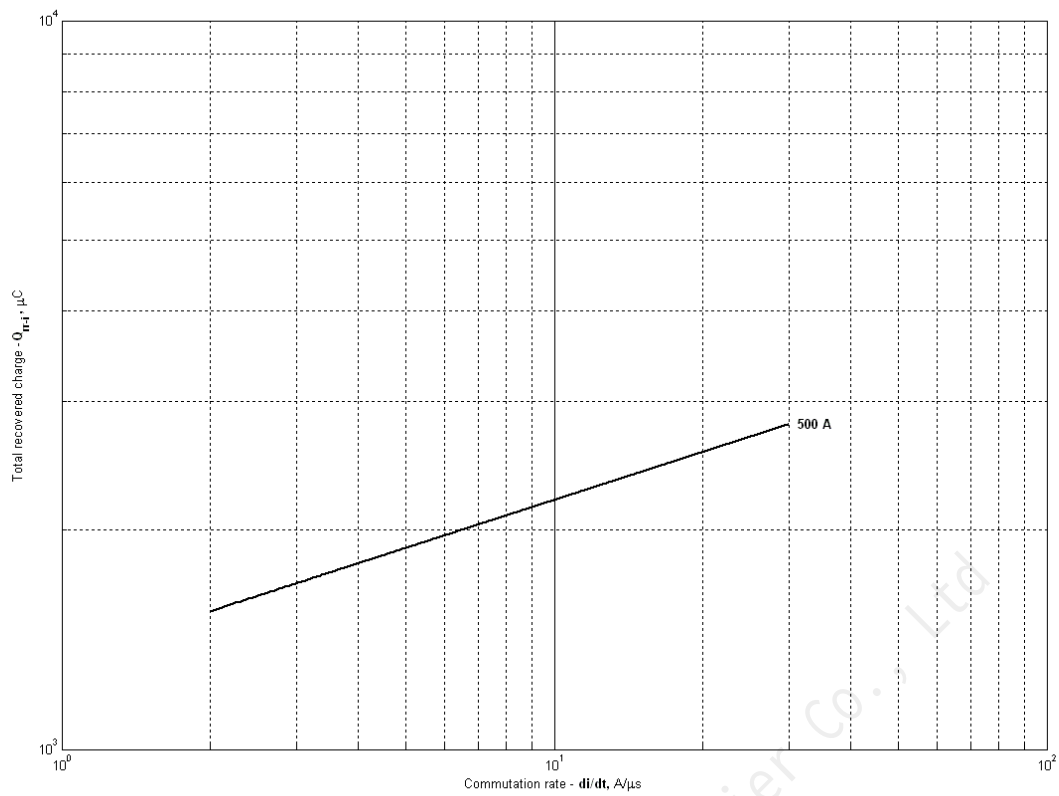


Fig 5 – Total recovered charge, Q_{rr-i} (integral)

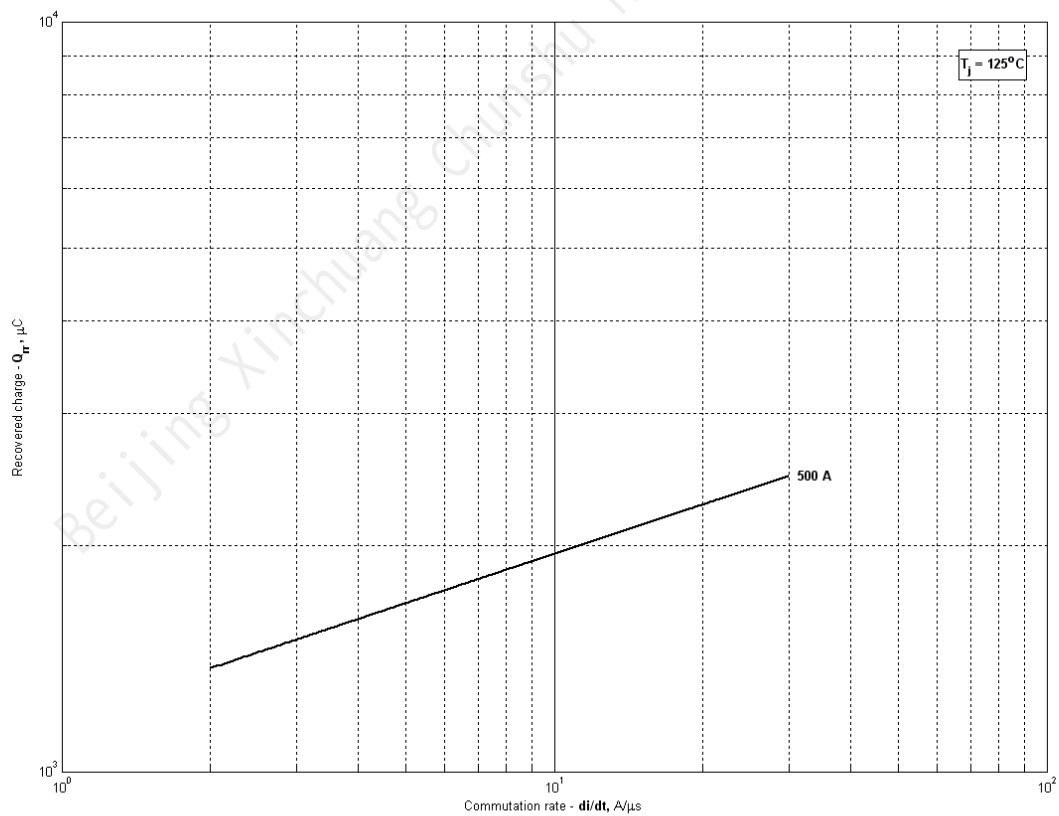


Fig 6 - Recovered charge, Q_{rr} (linear)

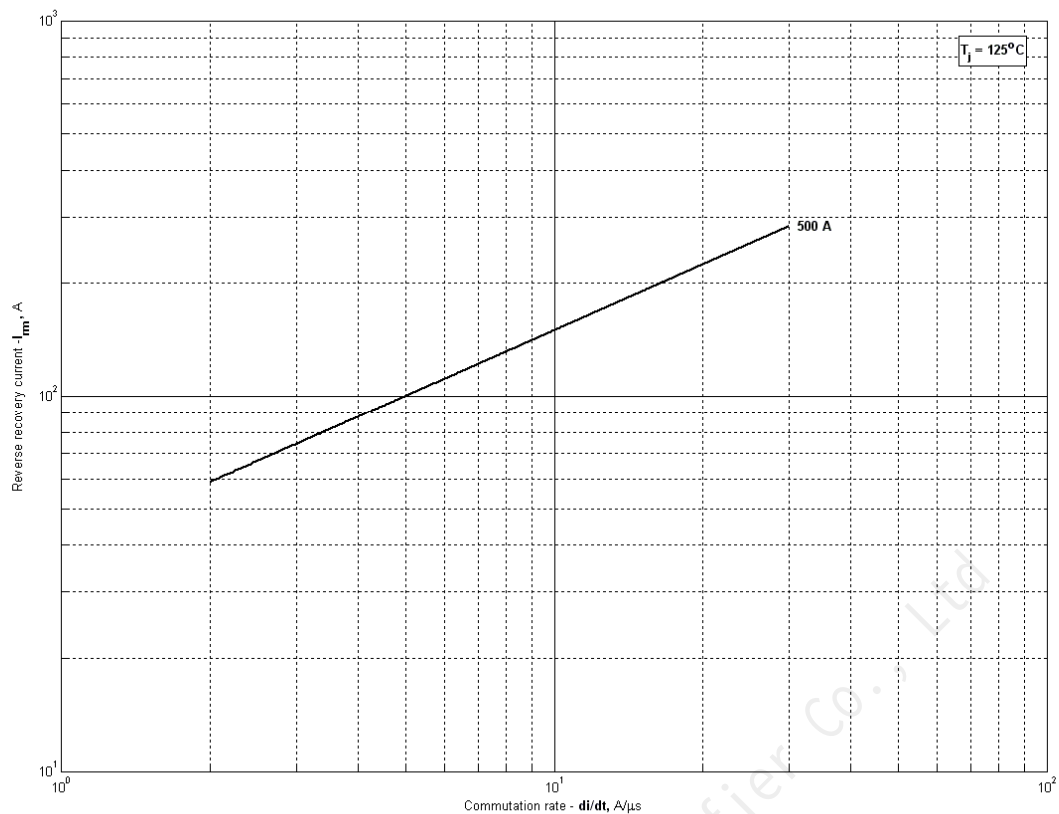


Fig 7 – Peak reverse recovery current, I

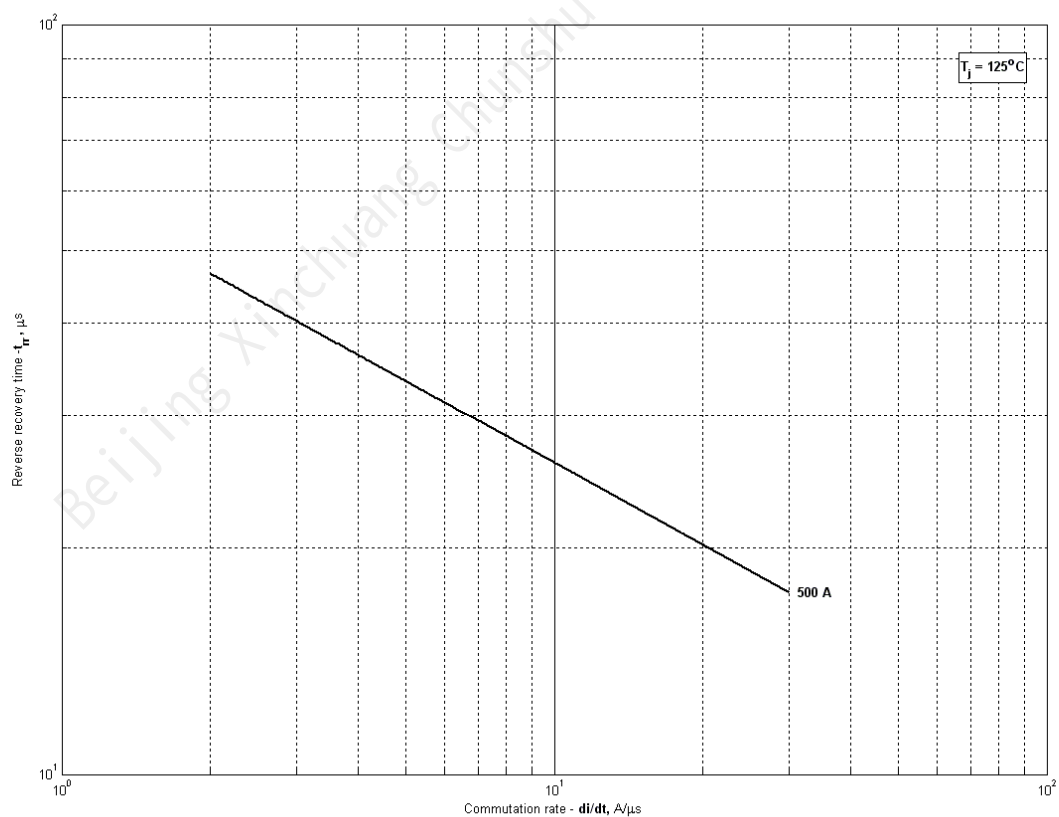


Fig 8 – Maximum recovery time, t_{rr} (linear)

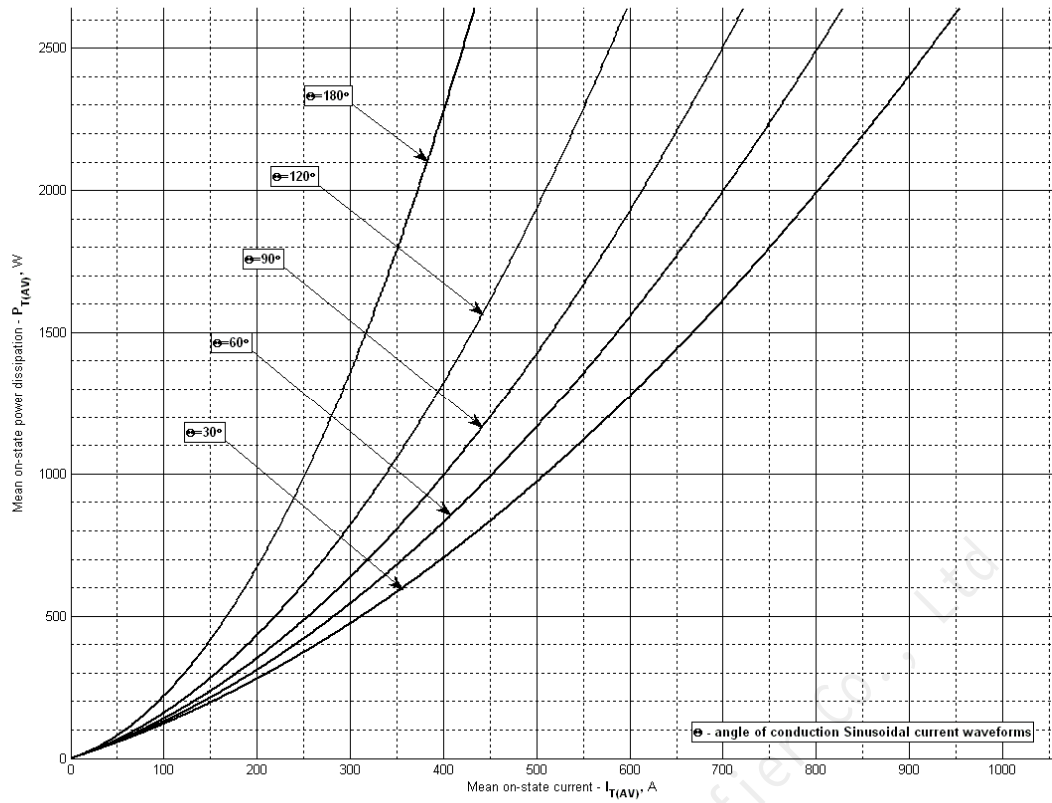


Fig 9 – On-state power loss (sinusoidal current waveforms)

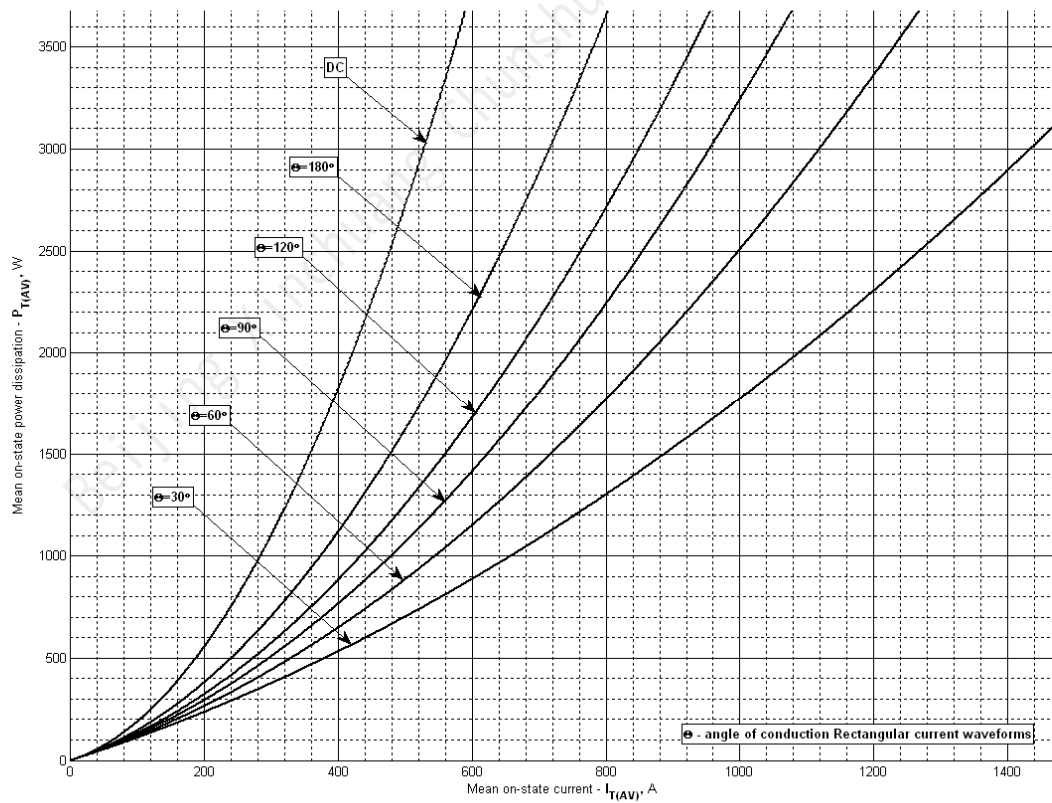


Fig 10 – On-state power loss (rectangular current waveforms)

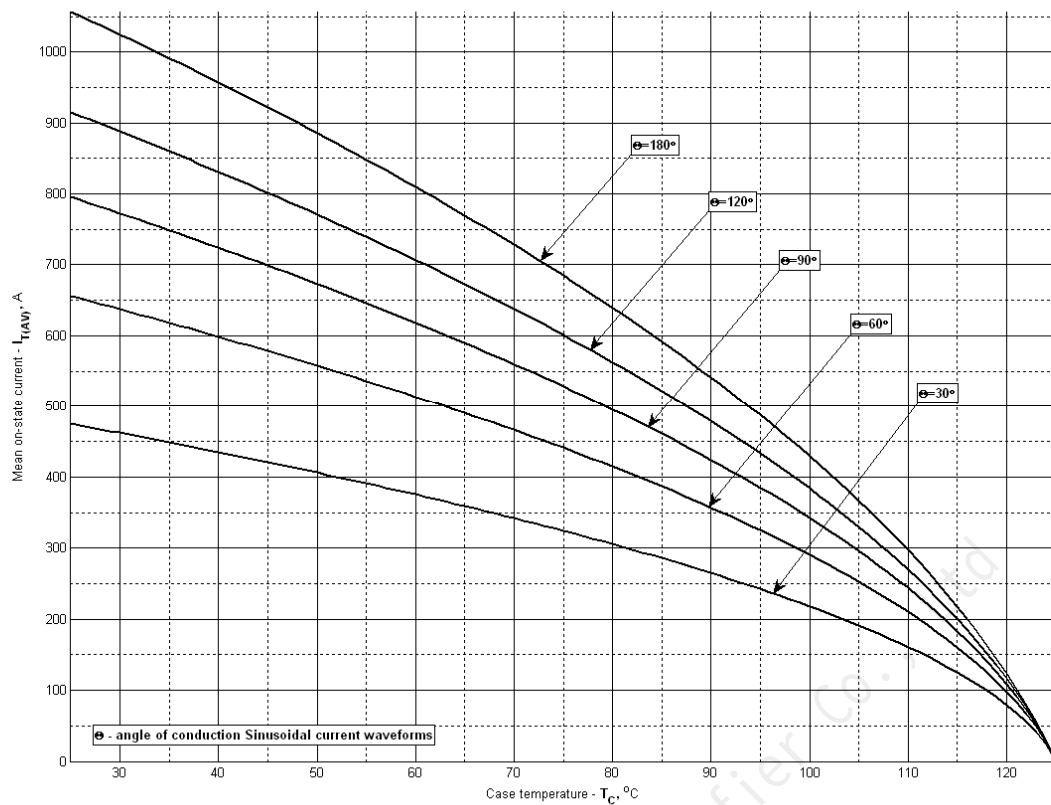


Fig 11 – Maximum case temperature DSC (sinusoidal current waveforms)

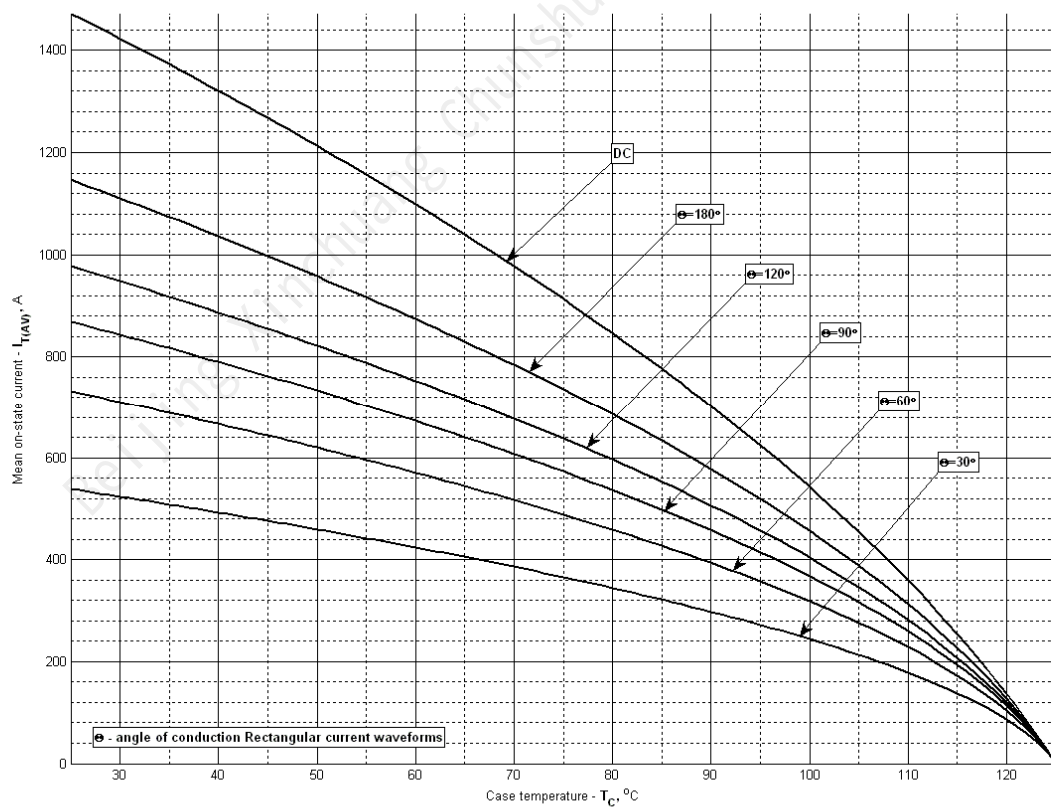


Fig 12 – Maximum case temperature DSC (rectangular current waveforms)

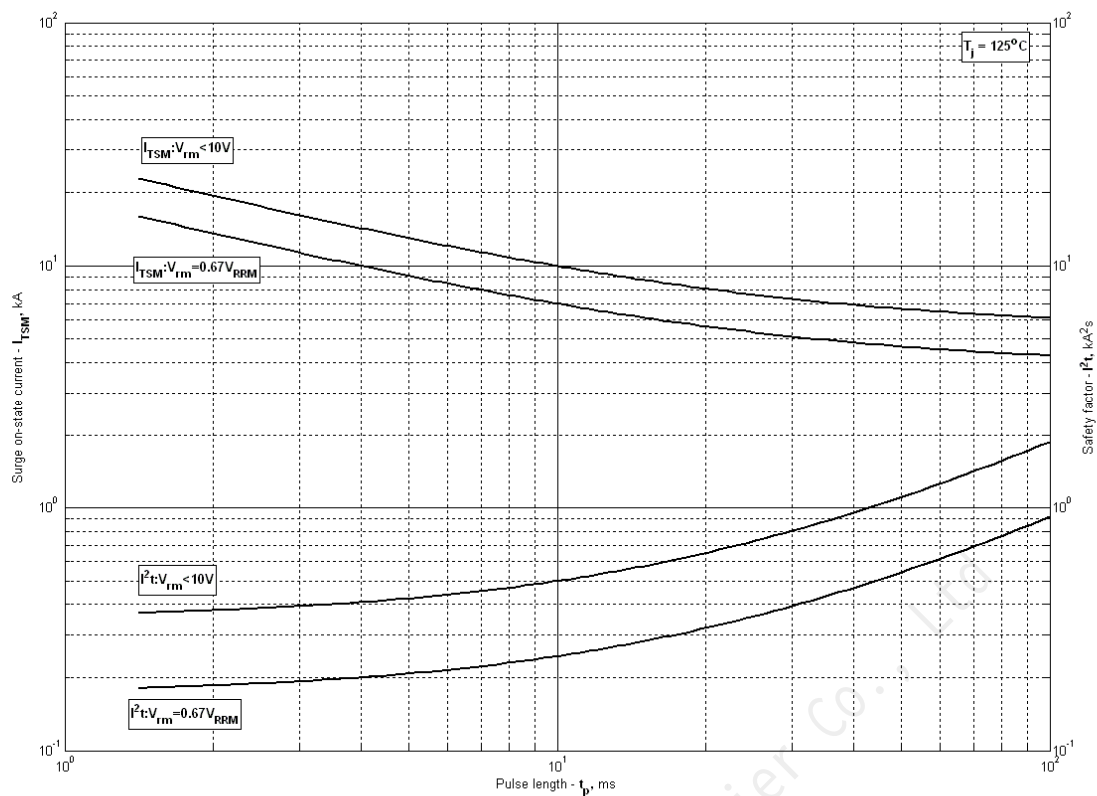


Fig 13 – Maximum surge and I



Fig 14 – Maximum surge ratings